

CUSTOMER 客户:

规格书编号

SPEC NO: HDFB12RSSB5SP02

产品规格书 SPECIFICATION

PRODUCT 产品:	SAW FILTER		
MODEL NO 型 号:	HDFB12RSS-B5		
MARKING 印字:	● B196		
PREPARED 编 制:	CHECKED 审 核:		
APPROVED 批 准:	DATE日期: 2017-12-29		
客户确认 CUSTOMER RECEIVED:			
审核 CHECKED	批准 APPROVED	日期 DATE	

无锡市好达电子有限公司 Shoulder Electronics Limited



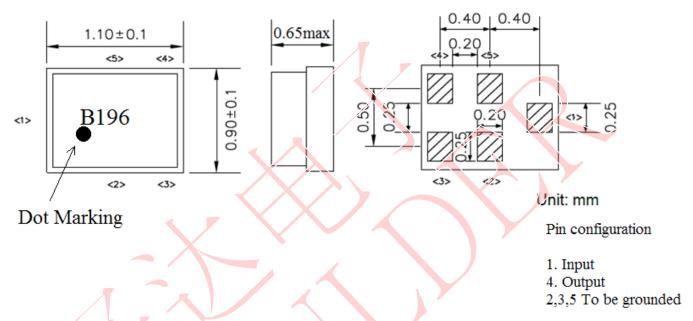
更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark
2017-3-21	SP00	HDFB12RS S-B5		The new specification	
2017-9-21	SP01	HDFB12RS S-B5		Add dot marking.	2. DIMENSION
2017-12-29	SP02	HDFB12RS S-B5		Update matching circuit	

1. Application

- Low-loss RF filter for mobile telephone LTE Band12 systems, receive path(RX).
- Usable passband 17MHz
- Impedance 50 ohm input and output
- Unbalanced to unbalanced operation
- RoHS compatible

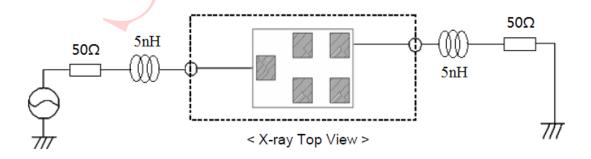
2. DIMENSION (PKG SIZE 1.1 x 0.9mm)



3. Maximum Kating

Iterns	Conditions
Operation temperature rang	-30°C ~ +85°C
Storage temperature rang	-40°C ~ +85°C
ESD voltage	ESD(MM): 50VDC
Sensitive discharge device	ESD(HBM): 175VDC
DC Voltage VDC	3V (25+/-2 deg.C)
Max Input Power	15dBm 2000h
Moisture Sensitivity Level	MSL 2

4. Test Circuit





SAW FILTER

5. ELECTRICAL SPECIFICATION

Table 1. Electrical Specification

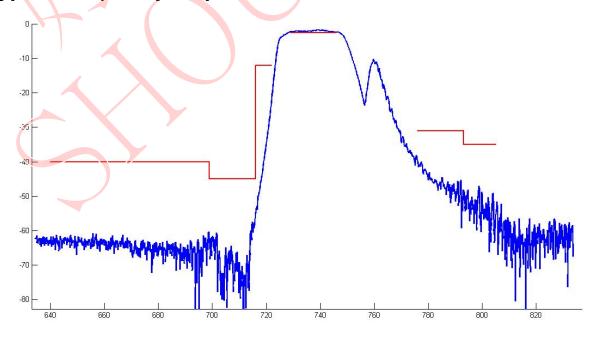
Temperature range for specification: $T = -20 \sim +80^{\circ}C$

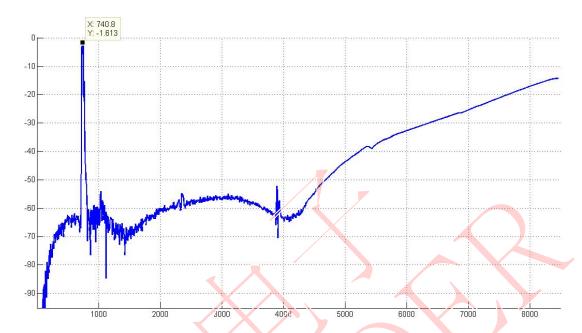
Terminating source impedance: $Zs = 50\Omega$ //28nH unbalanced Terminating load impedance: $Zl = 50\Omega$ //30nH unbalanced

Input power: 15dBm 2000h

input powe	•	15001117	-00011			
Item		Condition	Specification		Unit	
		(MHz)	Min	Typ	Max	
Insertion	loss	729~746	-	2.0	2.5	dB
Amplitude	e Ripple	729~746	-	0.6	1.5	dB
VSWR	Input	729~746	7 -	1.8	2.0	1
	Output		- ,	1.7	2.0	-
Absolute	attenuation	1~699	40	58	-/	άB
		699~716	45	55		dВ
		716~722	12	20	-	dB
		776~793	31	40	-	dB
		793~805	35	53		dB
		1710~1735	43	54	-	dB
	< P	1850~1910	41	55	-/	dB
		2187~2238	40	50	_	dB
		2400~2500	39	50	-	dB
_		4900~5950	25	33	-	dB
		6561~6714	18	27	-	dB
		7290~7460	12	20	-	dB
\	A	8019~8206	5	13	-	dB

6. Typical frequency response





7. ENVIRONMENTAL CHARACTERISTICS

7.1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 5.

7.2 Low temperature exposure

Subject the device to 40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 5.

7.3 Temperature cycling

Subject the device to a low temperature of -40° C for 30 minutes. Following by a high temperature of $+85^{\circ}$ C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 5.

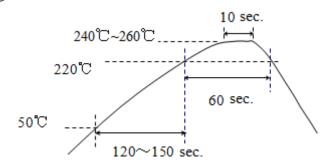
7.4 Resistance to solder heat

- 1, immerge the solder bath at 260°C for 10 sec.
- 2, the iron at 370°C for 3 sec

7.5 Solderability

Submerge the device terminals into the solder bath at 245° C $\pm 5^{\circ}$ C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 5.

7.6 Reflow soldering





The specimen shall be passed through the reflow furnace with the condition shown in the above profile for 1 time.

The specimen shall be stored at standard atmospheric conditions for 1h, after which the measurement shall be made. Test board shall be 1.6 mm thick. Base material shall be glass fabric base epoxy resin.

7.7 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 5.

7.8 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 5.

8. REMARK

8.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

8.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

8.3 Soldering

Only pad component may be solded. Please avoid soldering another part of component.

9. Packing

9.1 Dimensions

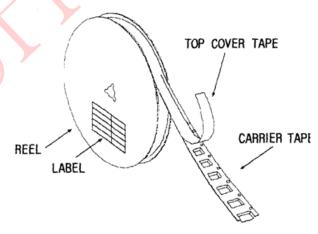
- (1) Carrier Tage: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

9.2 Reeling Quantity

10000 pcs/reel φ 178mm

9.3 Taping Structure

(1) The tape shall be wound around the reel in the direction shown below.

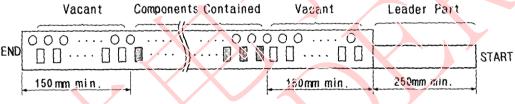


(2) Label



Device Name	
Marking	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



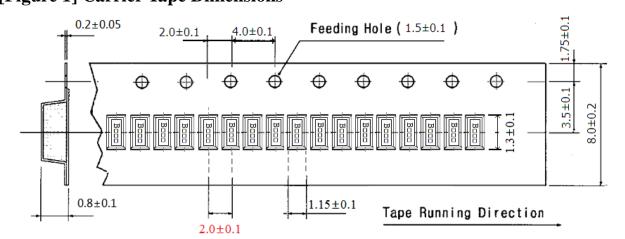
TAPE RUNNING DIRECTION

10. TAPE SPECIFICATIONS

- 10.1 Tensile Strength of Carrier Tape: 4.4N/mm width
- 10.2 Top Cover Tape Adhesion (See the below figure)
 - (1) pull off angle: 0~15°
 - (2) speed: 300mm/min.

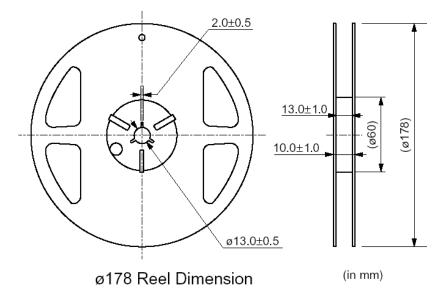


[Figure 1] Carrier Tape Dimensions



Prior to the size of 4.0 ± 0.1 , after encryption, modified to 2.0 ± 0.1 .

[Figure 2] 10000 pcs/reel ϕ 178mm



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